

SPECIFICATION

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SPEC. NO.: PS-50037-XXXXXX-XXX REVISION: D

PRODUCT NAME: 0.5mm PITCH BTB SMT S/T D/R CONNECTOR

50036 Series; 50037 Series; 50038 Series; 50045 Series;

PRODUCT NO: 50046 Series; 50153 Series.

PREPARED: CHECKED: APPROVED:

CHENYA BRAVE FRANK

DATE: DATE:

2015/06/01 2015/06/01 2015/06/01



TITLE: 0.5MM PITCH BTB SMT S/T D/R CONNECTOR

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1 Revision History

Rev.	ECN#		Revisio	Approve d	Date				
0	ECN- 0812036	NEW SPEC	;	JASON	2008/12/06				
Α	ECN- 1401255	ADD WORK	KING VOL	TANGENHU I	2014/01/18				
В	ECN- 1407467	REVISE PR	RODUCT N	IO.				FENGXIAO	2014/08/08
C	ECN- 1409032	22~40	↓ ↓					LLJ	2015/05/22
D	ECN- 1507359	Mating / Un 82~120 122~200 82~100 102~200	4.0 6.0 0 6.0 7.0			0.6 0.6 0.6	CHENYA	2015/06/01	



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2 SCOPE

This specification covers performance, tests and quality requirements for 0.50mm pitch BTB connector.

3 APPLICABLE DOCUMENTS

EIA-364 ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

- 4.1 Design and Construction
 - 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
 - 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.
- 4.2 Materials and Finish
 - 4.2.1 Contact: High performance copper alloy

Finish: (a) Contact Area: Gold plated based on order information

- (b) Under plate: Nickel-plated all over
- 4.2.2 Housing: Thermoplastic High Temp., UL94V-0
- 4.3 Ratings
 - 4.3.1 Working Voltage Less than 36 Volts AC (per pin)
 - 4.3.2 Voltage: 50 Volts AC (per pin)
 - 4.3.3 Current: 0.5 Amperes (per pin)
 - 4.3.4 Operating Temperature : -40°C to +85°C



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5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard				
	Product shall meet requirements of	Visual, dimensional and functional				
Examination of Product	applicable product drawing and	per applicable quality inspection				
	specification.	plan.				
	ELECTRICAL					
ltem	Requirement	Standard				
Low Level Contact Resistance	55 m Ω Max.(initial)per contact △R 10 m Ω Max.	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)				
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)				
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 VAC Min. at sea level for 1 minute Test between adjacent contacts of unmated connectors. (EIA-364-20)				
Temperature rise	30°C Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70,METHOD1,CONDITION1)				
	MECHANICAL					
Item	Requirement	Standard				
Durability	30 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)				
	Unit: Kg	Operation Speed:				
Mating / Upmating Farance	Initial Final Initial Final	25.4 ± 3 mm/minute. Measure the force required to mate/Unmate connector.				
Mating / Unmating Forces	<20	(EIA-364-13)				
Terminal / Housing Retention Force	0.2kgf MIN.	Operation Speed: 25.4 ± 3 mm/minute. Measure the contact retention force with tester.				



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		Operation Sp	peed:					
Fitting Nail /Housing	O Okaf MINI	25.4 ± 3 mm/minute.						
Retention Force	0.2kgi ivilin.	Measure the	contact retention force					
		with Tensile	with Tensile strength tester.					
	Measu with Te The ele be 100 contact harmor of 0.76 total ex betwee The en 10 to 5 shall be 1 minu applied mutual (EIA-36 Subject 50 G's pulses Three s shall be mutual test spr electric 100mA (EIA-36 ENVIRONMENTAL Requirement See Product Qualification and Test Sequence Group 9 (Lead Free) Sequence Group 9 (Lead Free) Sequence Group 9 (Lead Free) Pre He 60~120 Heat: Peak T		I load condition shall					
			be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude					
		of 0.76mm (1.52mm maximum						
		total excursion) in frequency between the limits of 10 and 55 Hz.						
Vibration	1 μs Max.							
			equency range, from					
			and return to 10 Hz,					
			ersed in approximately					
			nis motion shall be					
			hours in each of three					
			pendicular directions.					
		(EIA-364-28						
			ed connectors to					
			value) half-sine shock					
		pulses of 11	11 milliseconds duration.					
		Three shocks	s in each direction					
Shook (Machanical)	1 up Mov	shall be appl	ied along the three					
Shock (Mechanical)	test specimen (18 shocks).	pendicular axes of the						
		1 μs Max. mutually perpendicular axes of t test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contact	n (18 shocks). The					
		100mA maxi	mum for all contacts.					
		(EIA-364-27,	(EIA-364-27, test condition A)					
	ENVIRONM	IENTAL						
Item			Standard					
Resistance to Wave								
Soldering Heat								
Soluering Heat	Coquerios Croup C (200	20313 (, 10	10.5sec.					
D : 1	O - D - I - I O - I'S - I's	To the state of th	50 % 5 400 % 5					
Resistance to Reflow			50 C~180 C,					
Soldering Heat	Sequence Group 9 (Lea	,						
			Min., 40sec Min.					
		Peak Temp.	: 260°ℂ Max,					
		-	c Max.					
			per cycle: 2 times					
		(EIA-364-56)						
			and subject to follow					
		condition for						
	See Product Qualificatio		o cycles.					
Thermal Shock	Sequence Group 4	-55 +0/-3 °C,	30 minutes					
	Sequence Group 4	-35 +0/-3 ℃, +85 +3/-0 ℃.						
			· · · · · · · · · · · · · · · · · · ·					
			test condition I)					
	Coo Dradeet Occilient	Mated Conne						
Humidity	See Product Qualificatio	n and Test 40°C, 90∼95°						
Humidity	See Product Qualificatio Sequence Group 4	n and Test 40°ℂ, 90~95° 96 hours.						



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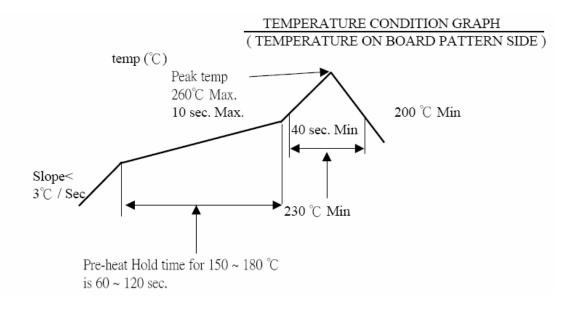
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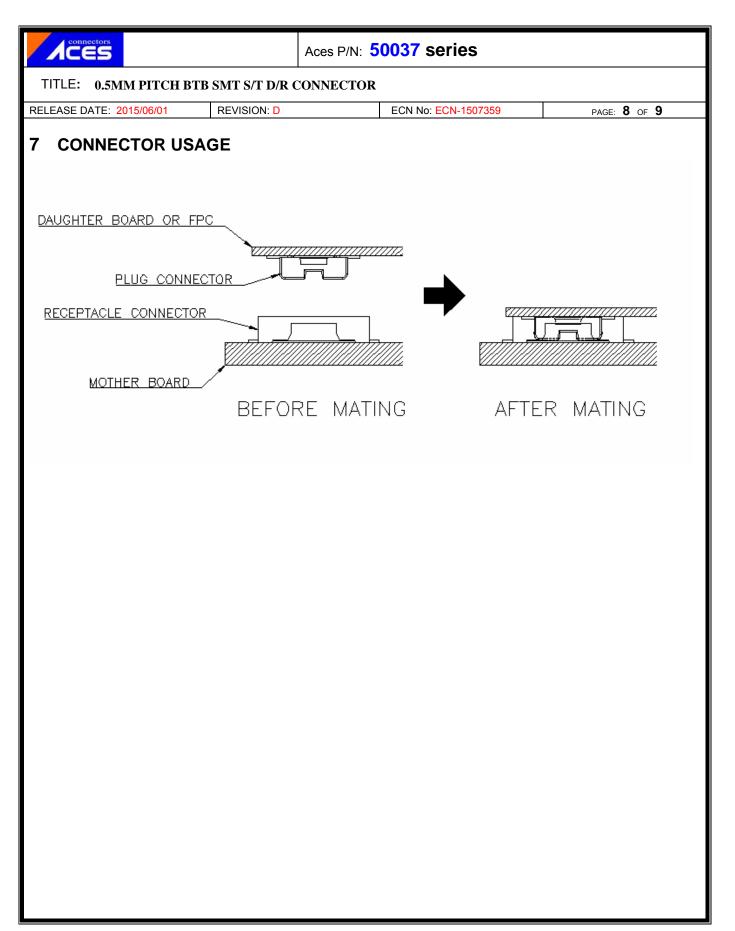
		,				
		Subject mated connectors to				
Temperature life	See Product Qualification and Test	temperature life at 85°C for 96				
remperature me	Sequence Group 5	hours.				
		(EIA-364-17, Test condition A)				
		Subject mated/unmated				
		connectors to 5% salt-solution				
Salt Spray	See Product Qualification and Test	concentration, 35°C				
(Only For Gold Plating)	Sequence Group 6	(I) Gold flash for 8 hours				
,		(II) Gold plating 5 u" for 96 hours.				
		(EIA-364-26)				
	Tin plating:					
	Solder able area shall have	And then into solder bath,				
Coldor obility	minimum of 95% solder coverage.	Temperature at 245 ±5°C, for 4-5				
Solder ability	Gold plating:	sec.				
	Solder able area shall have	(EIA-364-52)				
	minimum of 75% solder coverage					

Note. Flowing Mixed Gas shell be conduct by customer request.

6 INFRARED REFLOW CONDITION

6.1. Lead-free Process







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8 PRODUCT QUALIFICATION AND TEST SEQUENCE

	Test Group									
Test or Examination	1	2	3	4	5	6	7	8	9	
				To	est Se	quenc	e			
Examination of Product				1 . 7	1 \ 6	1 \ 4			1	
Low Level Contact Resistance		1 \ 5	1 \ 4	2、10	2 ` 9	2 ` 5			3	
Insulation Resistance				3 . 9	3 · 8					
Dielectric Withstanding Voltage				4 \ 8	4 \ 7					
Mating / Unmating Forces		2 \ 4								
Temperature Rise	1									
Durability		3								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray						3				
Solder ability							1			
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Sample Size	2	4	4	4	4	4	2	4	4	